

## LDEIE3220KA0N00

Aliases (DEIE3220KA0N00)

LDE, Film, Metallized PEN Stacked, Automotive Grade, 0.22 uF, 10%, 120 VAC, 250 VDC, 125°C, 2824, 5.2mm



Click [here](#) for the 3D model.

### Dimensions

|           |                   |
|-----------|-------------------|
| Chip Size | 2824              |
| L         | 7.3mm +/-0.4mm    |
| W         | 6.1mm +/-0.4mm    |
| T         | 5.2mm MAX         |
| B         | 0.4mm +0.5/-0.3mm |

### Packaging Specifications

|                    |      |
|--------------------|------|
| Packaging          | T&R  |
| Packaging Quantity | 1500 |

### General Information

|                  |                        |
|------------------|------------------------|
| Series           | LDE                    |
| Dielectric       | Metallized PEN Stacked |
| Style            | SMD Chip               |
| Features         | Automotive Grade       |
| RoHS             | Yes                    |
| Qualifications   | AEC-Q200               |
| AEC-Q200         | Yes                    |
| Component Weight | 0.667 g                |
| Shelf Life       | 104 Weeks              |
| MSL              | 2a                     |

### Specifications

|                       |            |
|-----------------------|------------|
| Capacitance           | 0.22 uF    |
| Capacitance Tolerance | 10%        |
| Voltage AC            | 120 VAC    |
| Voltage DC            | 250 VDC    |
| Temperature Range     | -55/+125°C |
| Rated Temperature     | 125°C      |
| Dissipation Factor    | 0.8% 1kHz  |
| Insulation Resistance | 1 GOhms    |
| Max dV/dt             | 100 V/us   |

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